

# **SPECIFICATION FOR APPROVAL**

Description	940nm 5mW VCSEL Laser Diode		
Part No	DRS940-0005-07-1616E-PD		
Date	2024-02-04		

Producer	Producer Engineering Dept.		Approval	
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Customer acknowledges Results				



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# Exterior



### **Product conformation:**

- Packaging glou: 1616 encapsulation
- Ceramic Substrate package, High brightness, High efficiency
- Size: 1.6mm\*1.6mm\*0.66mm
- RoHS compliant
- Compatible with SMT
- Viewing Angle: 21°
- Package: Max 3000pcs /reel
- Luminous color: Red wavelength 680nm
- Chip specification:7mil\*7mil
- Luminous Angle: 22 degrees
- Electrostatic sensitive material



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## Package outline dimensions







Note:

- 1. Dimensions are in millimeters.
- 2. Tolerances unless mentioned are ± 0.1mm.

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# **Optical Characteristics(IF=8mA)**

Item	Symbol	Min.	Тур.	Max.	Unit	
	VCSEL					
Threshold Current	Ith	0.5	0.8	1.2	mA	
Output Power	Ро	6	7	9	mW	
Forward Voltage	Vo	1.7	1.9	2.2	V	
Dominant wavelength	WLP	930	940	950	nm	
Reverse Current (VR=5V)	I <sub>R</sub>			1	uA	
Viewing Angle		18	21	25	o	
		PD				
Forward Voltage	Vf	0.6		1.2	V	
PD Reverse Dark Current				0.1	uA	
PD Light Current		4		8	uA	
ESD						
Forward Voltage	Vr	5.5		7	V	
Reverse Voltage		5.5		6.8	V	

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## **Maximum Rating**

Parameter	Symbol	Rating	Unit
Operating Temperature Range	Topr	-20~85	°C
Storage Temperature	Tstg	-40~ 100	°C
ESD Human Body Mode HBM 8000V	HBM	8000	V
Min PD Reverse voltage	VR	35	V

# L-I-V The Photoelectric Characteristics Graph iF =8mA; Ta = 0°C-80°C



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Relative Spectral Power Distribution vs. Wavelength IF =8mA; Ta = 25°C









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PD Current curve Ta = 25°C

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### **Reel Dimensions**

**Progressive direction and Dimensions:** 

Loaded quantity 3000PCS per reel



F

装配图

W	8.00±0.05	A0	1.82±0.05	K0	0.75±0.05
Т	0.20±0.02	<b>B</b> 0	1.85±0.05	D0	1.60±0.10
A0	1.82±0.05	D1	$1.10 \pm 0.10$	P2	2.00±0.10
<b>B</b> 0	1.85±0.05	P1	$4.00 \pm 0.10$	PO	4.00±0.10



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# **Application precautions**

#### Preservation and use

- 1. Before opening the package, it should be stored at 30 °C/60%RH or less. After opening the package, it should be placed in an environment of 20-30 °C/30%RH or less.
- 2. To avoid the impact of the environment, it is recommended to dehumidify after unpacking at  $80^{\circ}C/24H$ . All the VCSELs are needed to be vacuumed to avoid failure
- 3. If the desiccant faded or expired use, dry baking:  $80\pm5^{\circ}C/24$  hours.
- 4. VCSEL Glue surface easy to dust, need to do the relevant dust prevention measures.

#### Pick and place

When taking the VCSEL, you should only touch the bracket. Tools such as tweezers should not put pressure on the lens.Don't stab or push the lens.

#### Heat treatment

When driven by excessive current, the Tj (node temperature) of VCSEL will exceed the period limit value, which leads to a serious shortening of VCSEL life. Thermal treatment measures should effectively reduce the thermal resistance of application products.Common practice: install VCSEL packages on metal matrix PCB boards.1W VCSEL products require the surface heat dissipation area of the metal substrate to be at least 30cm squared (over 80cm squared is recommended for 3W products), and its thermal conductivity is higher than 2.0w /mK.VCSEL and gold substrate are combined by thermal conductive adhesive with good thermal conductivity. The thermal conductivity coefficient is required to be higher than 1.0w /mK and the thickness is less than 100um.

#### Clean

If you need to clean, use a clean, soft cloth dipped in alcohol to gently remove foreign matter. Do not use a cleaner such as acetone to avoid possible corrosion damage.

#### **Electrical precautions**

- 1. VCSEL Reverse drive is not allowed
- 2. Current limiting measures are necessary, otherwise slight voltage changes will lead to large current changes, which may lead to VCSEL failure.
- 3. Under the premise that the luminous quantity meets the requirements, it is recommended to use the drive current lower than the rated current, which is conducive to improving the reliability of the product.

#### Anti-static precautions

VCSEL is electrostatic sensitive devices, in the process of preservation, use to take anti-static measures. Static electricity and surge can lead to changes in product characteristics, such as forward voltage reduction, which can be serious and even damage the product. So for the whole process (production, testing, packaging, etc.) and VCSEL direct contact staff should do a good job to prevent and eliminate electrostatic measures. All related equipment and machinery should be properly grounded. The grounding ac resistance is less than 1.0 ohm, the table mat with surface resistance of 106-109 ohm is needed on the work table. Ion fans must also be installed in electrostatic environments and equipment. During the operation, the operator should use anti-static bracelet, anti-static mat, anti-static overalls, working shoes, gloves, anti-static capacity.

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#### An electric soldering iron

It is recommended to use anti-static electric soldering iron, the temperature at the tip does not exceed  $350^{\circ}$ C, less than 3 seconds for each soldering. The power of the soldering iron should be less than 60W. Weld two electrode pins more than 2 seconds after each welding. Do not force the lens during welding. Problems with VCSELs usually begin when they are soldered. So you must work carefully as required.

#### **Reflow instructions**



#### Precautions

- 1. Reflow soldering is only allowed once.
- 2. Do not apply pressure to the lamp body during reflow
- 3. After reflow welding is completed, do not press the heat dissipation plate, do not press to the colloidal part.
- 4. If there is a lower melting point of solder paste, TP can be appropriately reduced.

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